

# $\mu$ PA2463T1Q

## MOS FIELD EFFECT TRANSISTOR

R07DS0188EJ0100 Rev.1.00 Dec 06, 2010

### **Description**

The  $\mu$ PA2463T1Q is a switching device, which can be driven directly by a 2.5 V power source.

The  $\mu$ PA2463T1Q features a low on-state resistance and excellent switching characteristics, and is suitable for applications such as power switch of portable machine and so on.

#### **Features**

- 2.5 V drive available
- Low on-state resistance
  - ---  $R_{DS(on)1}$  = 20.0 mΩ MAX. ( $V_{GS}$  = 4.5 V,  $I_D$  = 3.0 A)
  - ---  $R_{DS(on)2}$  = 21.0 mΩ MAX. ( $V_{GS}$  = 4.0 V,  $I_D$  = 3.0 A)
  - $R_{DS(on)3} = 24.0 \text{ m}\Omega \text{ MAX}.$  ( $V_{GS} = 3.1 \text{ V}, I_D = 3.0 \text{ A}$ )
  - ---  $R_{DS(on)4}$  = 28.5 mΩ MAX. ( $V_{GS}$  = 2.5 V,  $I_D$  = 3.0 A)
- Built-in G-S protection diode against ESD

### **Ordering Information**

Part No.	LEAD PLATING	PACKING	Package
μ PA2463T1Q-E1-AX *1	Ni/Pd/Au	8 mm embossed taping	8-pin HUSON (2720)
		3000 p/reel	

Note: \*1. Pb-free (This product does not contain Pb in the external electrode and other parts.)

### Absolute Maximum Ratings ( $T_A = 25^{\circ}C$ )

Item	Symbol	N-CHANNEL	Unit
Drain to Source Voltage (V <sub>GS</sub> = 0 V)	$V_{DSS}$	20	V
Gate to Source Voltage (V <sub>DS</sub> = 0 V)	$V_{GSS}$	±12	V
Drain Current (DC) *1	I <sub>D(DC)</sub>	±6	Α
Drain Current (pulse) *2	I <sub>D(pulse)</sub>	±50	Α
Total Power Dissipation (2 unit) *1	P <sub>T1</sub>	1.0	W
Channel Temperature	T <sub>ch</sub>	150	°C
Storage Temperature	T <sub>stg</sub>	-55 to +150	°C

Notes: \*1. Mounted on a glass epoxy board of 25.4 mm x 25.4 mm x 0.8 mmt

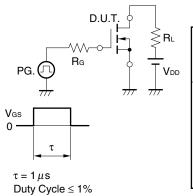
\*2. PW  $\leq$  10  $\mu$ s, Duty Cycle  $\leq$  1%

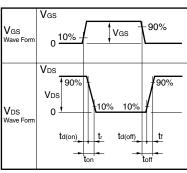
# Electrical Characteristics ( $T_A = 25^{\circ}C$ )

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Zero Gate Voltage Drain Current	I <sub>DSS</sub>			1	μΑ	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$
Gate Leakage Current	I <sub>GSS</sub>			±10	μΑ	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0 \text{ V}$
Gate to Source Cut-off Voltage	$V_{GS(off)}$	0.5	1.0	1.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Forward Transfer Admittance *1	y <sub>fs</sub>	2.5			S	$V_{DS} = 10 \text{ V}, I_{D} = 3.0 \text{ A}$
Drain to Source On-state	R <sub>DS(on)1</sub>	12	16.5	20	mΩ	$V_{GS} = 4.5 \text{ V}, I_D = 3.0 \text{ A}$
Resistance *1	R <sub>DS(on)2</sub>	13	17	21	mΩ	$V_{GS} = 4.0 \text{ V}, I_D = 3.0 \text{ A}$
	R <sub>DS(on)3</sub>	13.5	19	24	mΩ	$V_{GS} = 3.1 \text{ V}, I_D = 3.0 \text{ A}$
	R <sub>DS(on)4</sub>	15	22	28.5	mΩ	$V_{GS} = 2.5 \text{ V}, I_D = 3.0 \text{ A}$
Input Capacitance	C <sub>iss</sub>		680		pF	V <sub>DS</sub> = 10 V,
Output Capacitance	Coss		91		pF	$V_{GS} = 0 V$ ,
Reverse Transfer Capacitance	C <sub>rss</sub>		70		pF	f = 1 MHz
Turn-on Delay Time	$t_{d(on)}$		3		μs	$V_{DD} = 10 \text{ V}, I_D = 3.0 \text{ A},$
Rise Time	t <sub>r</sub>		6		μs	$V_{GS} = 4 V$ ,
Turn-off Delay Time	$t_{d(off)}$		13.5		μs	$R_G = 6 \Omega$
Fall Time	t <sub>f</sub>		10		μs	
Total Gate Charge	$Q_{G}$		7		nC	V <sub>DD</sub> = 16 V,
Gate to Source Charge	$Q_{GS}$		1.3		nC	$V_{GS} = 4 V$ ,
Gate to Drain Charge	$Q_{GD}$		2.7		nC	I <sub>D</sub> = 6.0 A
Body Diode Forward Voltage *1	$V_{F(S-D)}$		0.83		V	I <sub>F</sub> = 6.0 A, V <sub>GS</sub> = 0 V

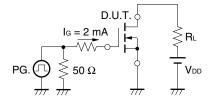
Note: \*1. Pulsed

### **TEST CIRCUIT 1 SWITCHING TIME**



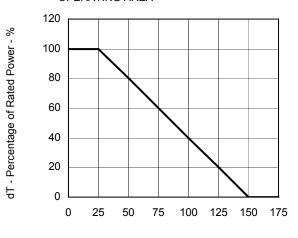


### **TEST CIRCUIT 2 GATE CHARGE**



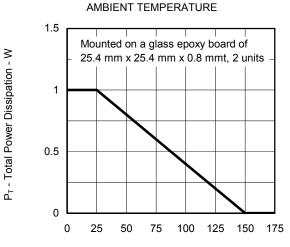
## Typical Characteristics (T<sub>A</sub> = 25°C)

DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



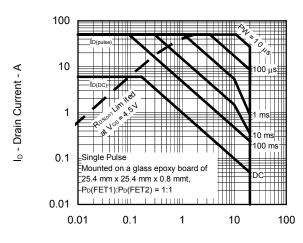
T<sub>A</sub> - Ambient Temperature - °C

# TOTAL POWER DISSIPATION vs.



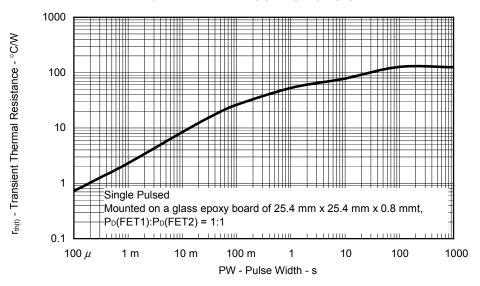
T<sub>A</sub> - Ambient Temperature - °C

#### FORWARD BIAS SAFE OPERATING AREA



 $V_{\text{\scriptsize DS}}$  - Drain to Source Voltage - V

### TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH



I<sub>D</sub> - Drain Current - A

V<sub>GS(off)</sub> - Gate to Source Cut-off Voltage - V

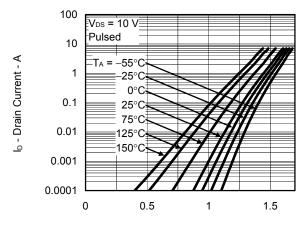
 $R_{\text{DS(on)}}$  - Drain to Source On-state Resistance -  $m\Omega$ 

# DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE

#### 70 60 V<sub>GS</sub> = 4.5 V 50 4.0 V 40 3.1 V 30 2.5 V 20 10 Pulsed 0 0 0.5 1 1.5 2 2.5 3

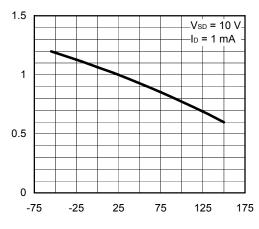
 $V_{\text{DS}}$  - Drain to Source Voltage - V

#### FORWARD TRANSFER CHARACTERISTICS



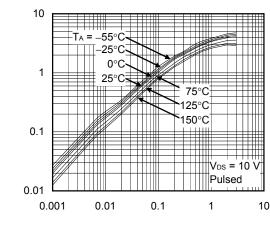
V<sub>GS</sub> - Gate to Source Voltage - V

# GATE TO SOURCE CUT-OFF VOLTAGE vs. CHANNEL TEMPERATURE



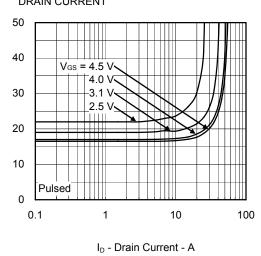
 $T_{\text{ch}}$  - Channel Temperature -  $^{\circ}C$ 

# FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

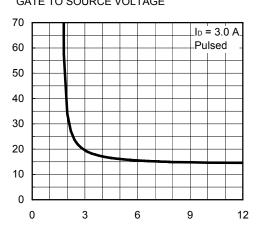


I<sub>D</sub> - Drain Current - A

# DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT



# DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE



 $V_{\text{GS}}$  - Gate to Source Voltage - V

 $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$  - Drain to Source On-state Resistance -  $m\Omega$ 

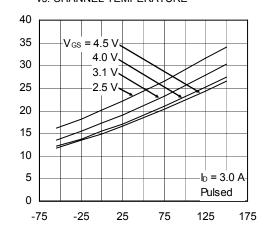
y<sub>s</sub> | - Forward Transfer Admittance - S

 $R_{\text{DS(on)}}$  - Drain to Source On-state Resistance -  $m\Omega$ 

td(on), tr, td(off), tr - Switching Time - µ s

I<sub>F</sub> - Diode Forward Current - A

### DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE



### $T_{\text{ch}}$ - Channel Temperature - $^{\circ}C$

### Ciss, Coss, Crss - Capacitance - pF 1000 100 10 $V_{GS} = 0$ = 1 MHz 1 0.1 0.01 1 10 100

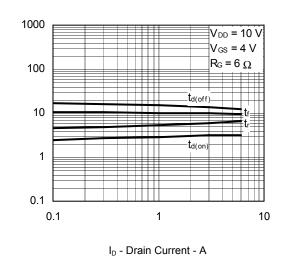
10000

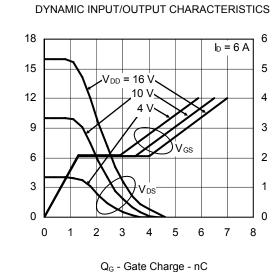
V<sub>DS</sub> - Drain to Source Voltage - V

 $V_{\text{DS}}$  - Drain to Source Voltage - V

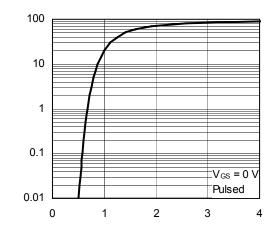
CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

### SWITCHING CHARACTERISTICS





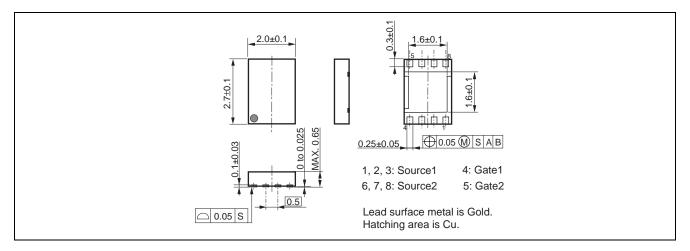
SOURCE TO DRAIN DIODE FORWARD VOLTAGE



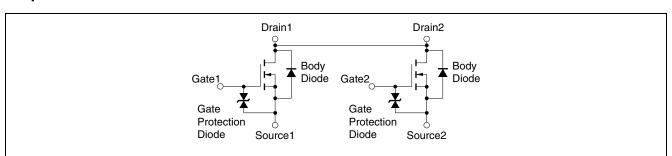
V<sub>F(S-D)</sub> - Source to Drain Voltage - V

## Package Drawings (Unit: mm)

### 8-pin HUSON (2720)



## **Equivalent Circuit**



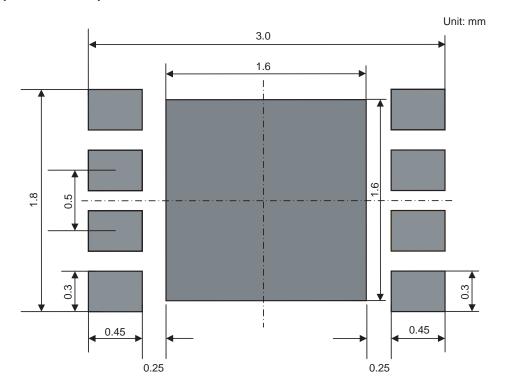
**Remark** The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

### <Notes for using this device safely>

When you use this device, in order to prevent a customer's hazard and damage, use it with understanding the following contents. If used exceeding recommended conditions, there is a possibility of causing failure of the device and characteristic degradation.

- 1. When you mount the device on a substrate, carry out within our recommended soldering conditions of infrared reflow. If mounted exceeding the conditions, the characteristic of a device may be degraded and it may result in failure.
- 2. When you wash the device mounted the substrate, carry out within our recommended conditions. If washed exceeding the conditions, the characteristic of a device may be degraded and it may result in failure.
- 3. When you use ultrasonic wave to substrate after the device mounting, prevent from touching a resonance generator directly. If it touches, the characteristic of a device may be degraded and it may result in failure.
- 4. Please refer to **Figure 1** as an example of the land pattern. Optimize the land pattern in consideration of density, appearance of solder fillets, common difference, etc in an actual design.

Figure 1. Example of the land pattern



**Revision History** 

## $\mu$ PA2463T1Q Data Sheet

		Description		
Rev.	Date	Page	Summary	
1.00	Dec 06, 2010	_	First Edition Issued	

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